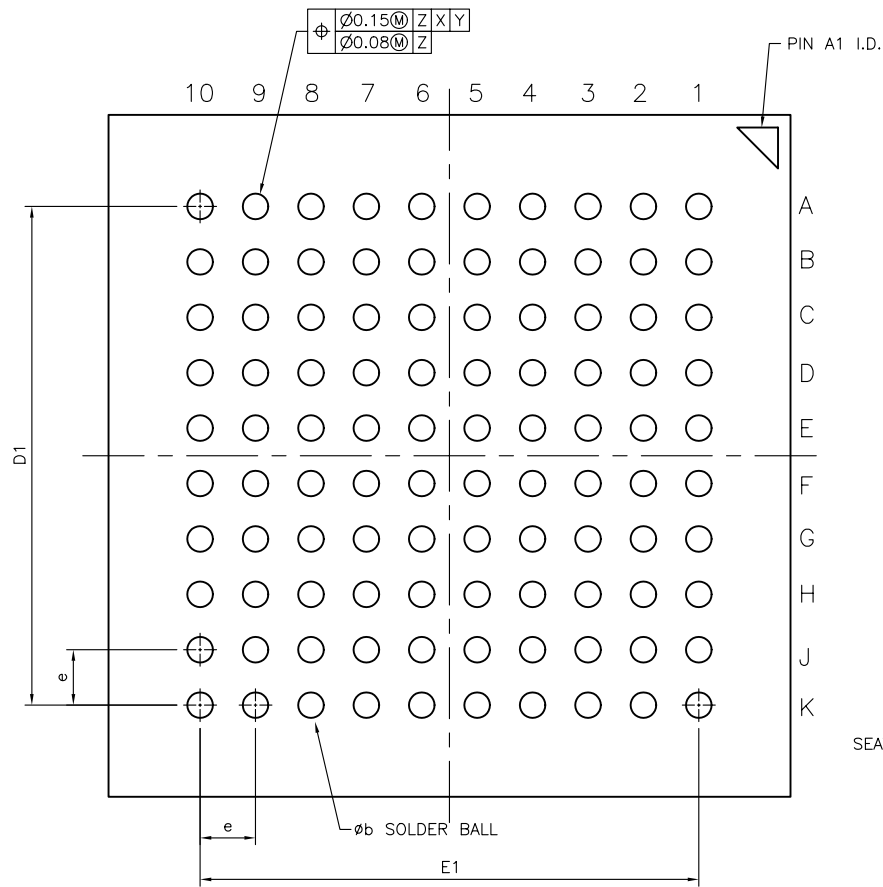
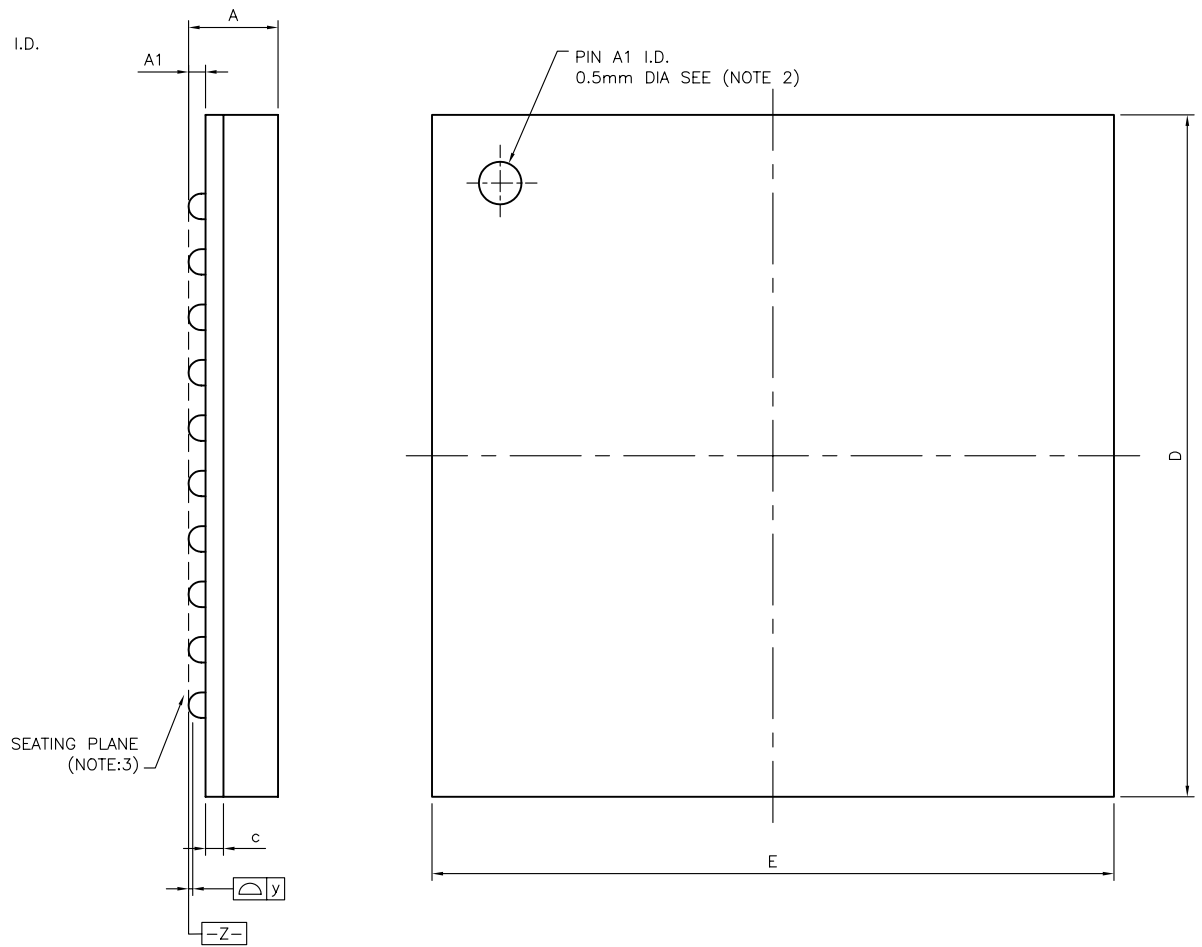


BOTTOM SIDE BOTTOM VIEW



TOP SIDE TOP VIEW



- NOTE :
1. ALL DIMENSION ARE IN MILLIMETERS.
 2. PIN A1 I.D. TO BE MARKED BY LASER.
 3. PRIMARY DATUM $[-Z-]$ AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
 4. "e" REPRESENTS THE MAXIMUM SOLDER BALL GRID PITCH.
 5. DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL PITCH, PARALLEL TO PRIMARY DATUM $[-Z-]$.

SYMBOLS	DIMENSIONS IN MILLIMETERS		
	MIN	NOM	MAX
\triangle A	0.90	—	1.10
\triangle A1	0.15	0.20	0.25
\triangle ϕb	0.25	0.30	0.35
c	—	0.21	—
D	7.90	8.00	8.10
D1	5.75	5.85	5.95
E	7.90	8.00	8.10
E1	5.75	5.85	5.95
e	—	0.65	—
y	0.00	—	0.10

CUSTOMER :		LINGSEN 5-1 NAN 2ND ROAD T.E.P.Z PRECISION IND., LTD. TAICHUNG., TAIWAN. R. O. C	
APPROVED BY	DATE	TITLE: MINI BGA 100L(8x8mm) PACKAGE OUTLINE DRAWING	
DRAW BY: Sandy Sue	11/25/05		
CHECK BY: S. S. Lin	11/25/05	DWG. NO. PO-MBGA-022	
APPROVAL: Kevin Liao	11/25/05		
APPROVAL: Jack Tu	11/29/05	REV. 1	
UNIT :	mm	SCALE :	15/1
		SHEET 1 OF 1	